

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jen-Cheng LIU</td> <td>11/30/2009</td> </tr> <tr> <td>Dun-Nian YAUNG</td> <td>11/30/2009</td> </tr> <tr> <td>Chen-Cheng KUO</td> <td>11/30/2009</td> </tr> <tr> <td>Chen-Shien CHEN</td> <td>11/30/2009</td> </tr> <tr> <td>Shou-Gwo WUU</td> <td>11/30/2009</td> </tr> </tbody> </table>		Name	Execution Date	Jen-Cheng LIU	11/30/2009	Dun-Nian YAUNG	11/30/2009	Chen-Cheng KUO	11/30/2009	Chen-Shien CHEN	11/30/2009	Shou-Gwo WUU	11/30/2009
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CORRESPONDENCE DATA													
<p>Fax Number: (214)200-0853</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 214-651-5000</p> <p>Email: eppsl@haynesboone.com</p> <p>Correspondent Name: HAYNES AND BOONE, LLP IP Section</p> <p>Address Line 1: 2323 Victory Avenue</p> <p>Address Line 2: Suite 700</p> <p>Address Line 4: Dallas, TEXAS 75219</p>													
ATTORNEY DOCKET NUMBER:	24061.988												

CH \$40.00 12626296

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PATENT
REEL: 023717 FRAME: 0323

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

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Docket No.: 2007-0258 / 24061.988
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|--|
| (1) | Jen-Cheng Liu | of | Gong-Dong Road, #219
Hsin-Chu City, Taiwan, R.O.C. |
| (2) | Dun-Nian Yaung | of | 4F, No. 15, Lane 130, Wansheng Street, Wunshan District
Taipei City 116, Taiwan, R.O.C. |
| (3) | Chen-Cheng Kuo | of | #127-4, Wa-Shin Street
Chu-Pei City, Shin-Chu County, Taiwan, R.O.C. |
| (4) | Chen-Shien Chen | of | 6F, No. 98, Wenxiao Street
Zhubei City, Hsinchu County 302, Taiwan, R.O.C. |
| (5) | Shou-Gwo Wu | of | No. 116, Alley 486, Min-Hu Road
Hsin-Chu City, Taiwan, R.O.C. |

have invented certain improvements in

BONDING PROCESS FOR CMOS IMAGE SENSOR

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
xx filed on November 25, 2009 and
assigned application no. 12/626,296 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on

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applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Jen-Cheng Liu

Residence Address: Gong-Dong Road, #219
Hsin-Chu City, Taiwan, R.O.C.

Dated: 11/30/09

Jen - Cheng Liu
Inventor Signature

Inventor Name: Dun-Nian Yaung

Residence Address: 4F, No. 15, Lane 130, Wansheng Street, Wunshan District
Taipei City 116, Taiwan, R.O.C.

Dated: 11/30/09

Dun - Nian Yaung
Inventor Signature

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Inventor Name: Chen-Cheng Kuo

Residence Address: #127-4, Wa-Shin Street
Chu-Pei City, Shin-Chu County, Taiwan, R.O.C.

Dated: 11/30/09

Chen - Cheng Kuo
Inventor Signature

Inventor Name: Chen-Shien Chen

Residence Address: 6F, No. 98, Wenxiao Street Zhubei City, Hsinchu County 302
Hsinchu City 300, Taiwan, R.O.C.

Dated: 11/30/09

Chen - Shien Chen
Inventor Signature

Inventor Name: Shou-Gwo Wu

Residence Address: No. 116, Alley 486, Min-Hu Road
Hsin-Chu City, Taiwan, R.O.C.

Dated: 11/30/09

[Signature]
Inventor Signature